

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 541 | 257/706.ccls. and (heat adj (sink slug element spreader plate radiation)) and (mold\$4 encapsula\$4 packag\$4) and (insulat\$4 dielectric) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 12:33 |
| L2 | 342 | L1 and @ad<="20010702" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 12:33 |
| L3 | 1294 | 257/712-718.ccls. and (heat adj (sink slug element spreader plate radiation)) and (mold\$4 encapsula\$4 packag\$4) and (insulat\$4 dielectric) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 12:33 |
| L4 | 951 | L3 and @ad<="20010702" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 12:33 |
| L5 | 774 | L4 not L2 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 15:58 |
| L8 | 1 | (encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) with (second adj length) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 16:05 |
| L9 | 338 | (encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) with length | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 16:56 |
| L10 | 117 | 9 and (chip die IC (integrated adj circuit)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 16:09 |
| L11 | 2 | ("6611011").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/03/09 16:10 |

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| L12 | 2 | ("6611001").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/03/09 16:10 |
| L14 | 3 | (molding adj line) with (lead support paddle) with (expos\$3 protrud\$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 16:57 |
| L15 | 2412 | ((encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 16:59 |
| L16 | 127 | ((encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:13 |
| L17 | 0 | 16 not 15 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 16:58 |
| L18 | 0 | ((mold\$3 adj line) with (lead support paddle) with (expos\$3 protrud\$3)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 16:59 |
| L19 | 10 | (mold\$3 adj line) with (lead support paddle) with (expos\$3 protrud\$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:01 |
| L21 | 1237 | ((encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) with (length surface)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:08 |
| L22 | 791 | 21 and (chip die IC (integrated adj circuit)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:15 |

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| L23 | 709 | 22 and second | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:10 |
| L24 | 50 | amano-kenji.in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:30 |
| L30 | 7 | ("5294827" "5521429" "5841187" "5844307" "5900676" "5973388" "5977613").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2006/03/09 17:19 |
| L31 | 181 | fujisawa-atsushi.in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:33 |
| L32 | 29 | hasebe-hajime.in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:33 |
| L34 | 61 | (encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/666-670.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:39 |
| L35 | 37 | (encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/672,674,676,678.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:41 |
| L36 | 34 | (encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/690-693.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:44 |

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| L37 | 54 | ("20040036180" "3838984" "4159221" "4398235" "4833568" "4956694" "4996587" "5068713" "5230759" "5258094" "5266834" "5332864" "5381039" "5381047" "5394010" "5414300" "5435057" "5455387" "5521429" "5581118" "5587341" "5594275" "5625221" "5677569" "5715147" "5742007" "5760471" "5835988" "5852320" "5859471" "5877043" "5880403" "5950074" "5962810" "5977613" "5986209" "6114221" "6130115" "6143981" "6180881" "6225146" "6235554" "6242281" "6281568" "6320251" "6356453" "6404046" "6433418" "6459148" "6518659" "6564454" "6577013" "6646339" "6730544").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2006/03/09 17:42 |
| L38 | 29 | (encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/787-788.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/09 17:44 |